## Product Quality Information

# nexperia

## **Quality Information for Product Type PUMD20**

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### **Quick reference**

| Information                  | Content            |
|------------------------------|--------------------|
| Device Type                  | PUMD20             |
| Ordering Information (12NCs) | 9340 589 01115     |
| Qualification Grade          | automotive         |
| Package                      | SOT363 (TSSOP6)    |
| Waferfab                     | Nexperia DHAM      |
| Assembly                     | Nexperia ATSN      |
| ESD HBM                      | > 500 V, <= 1000 V |
| Calculated Failure Rate      | 0.44 FIT           |
| MTBF/MTTF                    | 2.27E+09 hours     |

### **Explanation**

Automotive qualified products are in accordance with the AEC-Q101.

Electrostatic Discharge (ESD) tests are performed as described in the AEC-Q101 with each 3 positive and 3 negative pulses for each stress voltage level.

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, AEC-Q101 Test # 5). The parameters for calculation of FIT and MTBF/MTTF are as follows: Confidence level 60%, junction temperature derated to 55 °C, activation energy 0.7 eV, test time 168 - 1000 hrs.

For discrete semiconductor devices the Mean Time Between Failure (MTBF) is replaced by the Mean Time To Failure (MTTF) acronym. MTTF is calculated from the Intrinsic Failure Rate.

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